

1 (C) AMENDMENTS TO THE CLAIMS

2 Please cancel claims 2, 3, 6-8, and 10-12.

3 1. (Currently Amended) An integrated circuit structure comprising:
4 a circuit die;
5 at least one input-output pad for connecting to said circuit die;
6 wafer-level packaging including an electrically conductive material bump-out
7 beam and at least one active circuit element wherein the active circuit element
8 integrates therein at least a segment of said beam.

9 4. (Original) The structure as set forth in claim 1 comprising:
10 said beam is encased in a dielectric material, and
11 said active circuit element is a capacitor having a first plate formed by a
12 predefined region of said beam.

13 5. [Currently amended] The structure as set forth in claim 4 further comprising:
14 a grounded second plate embedded in [a top level metallization layer] said
15 dielectric material of said die proximate said region.

16 9. (Original) A wafer-level packaged integrated circuit device comprising:
17 a circuit die having at least one input-output pad and a top metal layer;
18 a wafer-level package including a dielectric material layer superjacent said die
19 and a conductive material beam encapsulated in said dielectric material layer and
20 leading to a connector bump on an external surface of said dielectric material layer; and
21 an ESD protection capacitor integrated into said top metal layer, using a
22 predetermined segment of said beam as a first plate and having a grounded second
23 plate embedded in said dielectric material layer proximate said segment.

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